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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	15
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 6x12b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc770t-ss

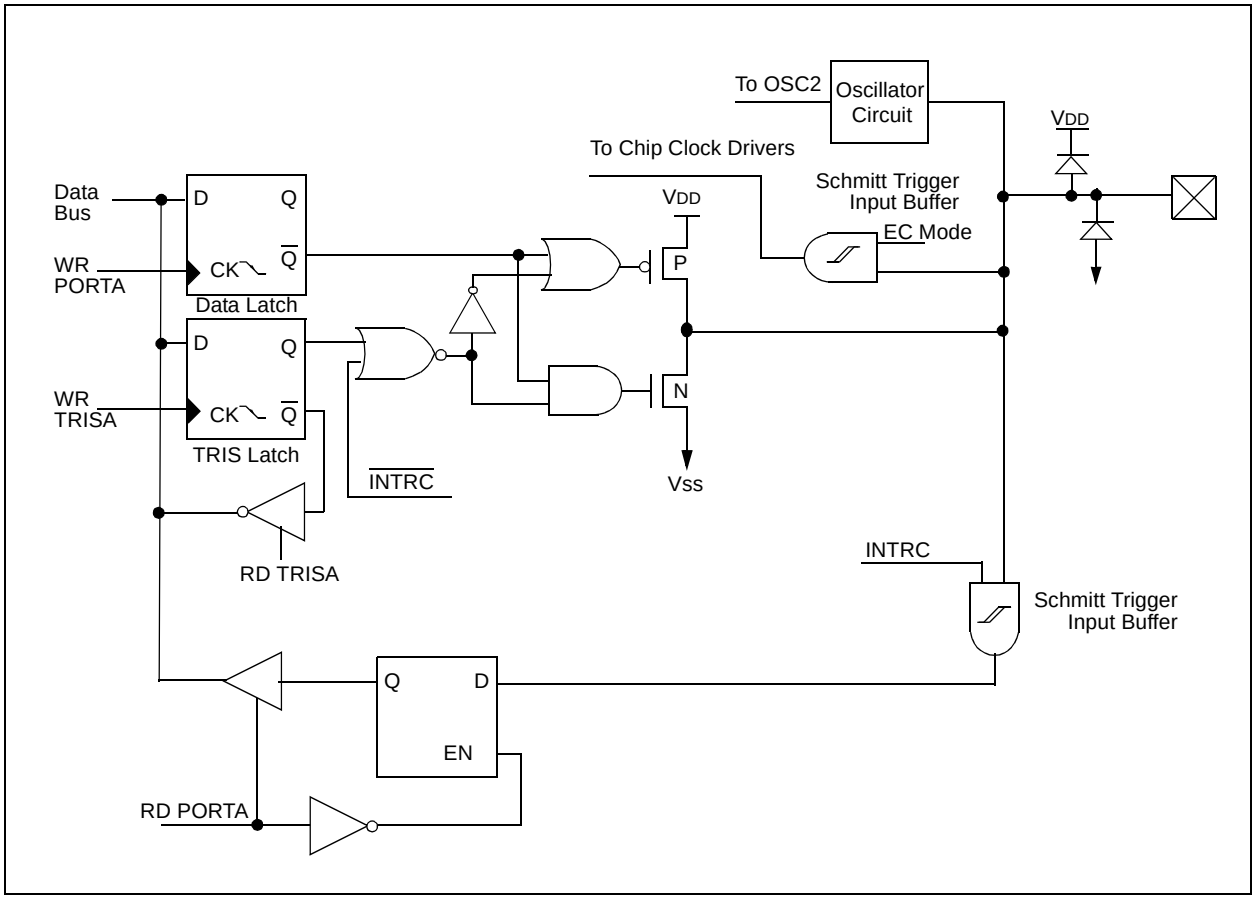
TABLE 1-1: PIC16C717/770/771 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0	RA0	ST	CMOS	Bi-directional I/O
	AN0	AN		A/D input
RA1/AN1/LVDIN	RA1	ST	CMOS	Bi-directional I/O
	AN1	AN		A/D input
	LVDIN	AN		LVD input reference
RA2/AN2/VREF-/VRL	RA2	ST	CMOS	Bi-directional I/O
	AN2	AN		A/D input
	VREF-	AN		Negative analog reference input
	VRL		AN	Internal voltage reference low output
RA3/AN3/VREF+/VRH	RA3	ST	CMOS	Bi-directional I/O
	AN3	AN		A/D input
	VREF+	AN		Positive analog reference input
	VRH		AN	Internal voltage reference high output
RA4/T0CKI	RA4	ST	OD	Bi-directional I/O
	T0CKI	ST		TMR0 clock input
RA5/$\overline{MCLR}$/VPP	RA5	ST		Input port
	$\overline{MCLR}$	ST		Master clear
	VPP	Power		Programming voltage
RA6/OSC2/CLKOUT	RA6	ST	CMOS	Bi-directional I/O
	OSC2		XTAL	Crystal/resonator
	CLKOUT		CMOS	FOSC/4 output
RA7/OSC1/CLKIN	RA7	ST	CMOS	Bi-directional I/O
	OSC1	XTAL		Crystal/resonator
	CLKIN	ST		External clock input/ER resistor connection
RB0/AN4/INT	RB0	TTL	CMOS	Bi-directional I/O**(1)**
	AN4	AN		A/D input
	INT	ST		Interrupt input
RB1/AN5/$\overline{SS}$	RB1	TTL	CMOS	Bi-directional I/O**(1)**
	AN5	AN		A/D input
	$\overline{SS}$	ST		SSP slave select input
RB2/SCK/SCL	RB2	TTL	CMOS	Bi-directional I/O**(1)**
	SCK	ST	CMOS	Serial clock I/O for SPI
	SCL	ST	OD	Serial clock I/O for I^2C
RB3/CCP1/P1A	RB3	TTL	CMOS	Bi-directional I/O**(1)**
	CCP1	ST	CMOS	Capture 1 input/Compare 1 output
	P1A		CMOS	PWM P1A output
RB4/SDI/SDA	RB4	TTL	CMOS	Bi-directional I/O**(1)**
	SDI	ST		Serial data in for SPI
	SDA	ST	OD	Serial data I/O for I^2C
RB5/SDO/P1B	RB5	TTL	CMOS	Bi-directional I/O**(1)**
	SDO		CMOS	Serial data out for SPI
	P1B		CMOS	PWM P1B output

Note 1: Bit programmable pull-ups.

2: Only in PIC16C770/771 devices.

FIGURE 3-6: BLOCK DIAGRAM OF RA7/OSC1/CLKIN PIN



6.0 TIMER1 MODULE

The Timer1 module timer/counter has the following features:

- 16-bit timer/counter
  (Two 8-bit registers; TMR1H and TMR1L)
- Readable and writable (Both registers)
- Internal or external clock select
- Interrupt on overflow from FFFFh to 0000h
- RESET from ECCP module trigger

Timer1 has a control register, shown in Register 6-1. Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Figure 6-2 is a simplified block diagram of the Timer1 module.

Additional information on timer modules is available in the PIC Mid-Range MCU Family Reference Manual, (DS33023).

6.1 Timer1 Operation

Timer1 can operate in one of these modes:

- As a timer
- As a synchronous counter
- As an asynchronous counter

The Operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In Timer mode, Timer1 increments every instruction cycle. In Counter mode, it increments on every rising edge of the external clock input.

REGISTER 6-1: TIMER1 CONTROL REGISTER (T1CON: 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **T1CKPS<1:0>:** Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3 **T1OSCEN:** Timer1 Oscillator Enable Control bit
1 = Oscillator is enabled
0 = Oscillator is shut off **(1)**

bit 2 **$\overline{\text{T1SYNC}}$:** Timer1 External Clock Input Synchronization Control bit
TMR1CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
TMR1CS = 0:
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1 **TMR1CS:** Timer1 Clock Source Select bit
1 = External clock from pin RB6/T1OSO/T1CKI /P1C (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR1ON:** Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

Note 1: The oscillator inverter and feedback resistor are turned off to eliminate power drain.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

7.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (Both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2
- SSP module optional use of TMR2 output to generate clock shift

Timer2 has a control register, shown in Register 7-1. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 7-1 is a simplified block diagram of the Timer2 module.

Additional information on timer modules is available in the PIC Mid-Range MCU Family Reference Manual, (DS33023).

7.1 Timer2 Operation

Timer2 can be used as the PWM time-base for PWM mode of the ECCP module.

The TMR2 register is readable and writable, and is cleared on any device RESET.

The input clock (Fosc/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS<1:0> (T2CON<1:0>).

The match output of TMR2 goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling inclusive) to generate a TMR2 interrupt (latched in flag bit TMR2IF, (PIR1<1>)).

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device RESET (Power-on Reset, $\overline{\text{MCLR}}$ Reset, Watchdog Timer Reset, or Brown-out Reset)

TMR2 is not cleared when T2CON is written.

REGISTER 7-1: TIMER2 CONTROL REGISTER (T2CON1: 12h)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit 7							bit 0

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **TOUTPS<3:0>:** Timer2 Output Postscale Select bits
0000 = 1:1 Postscale
0001 = 1:2 Postscale
•
•
•
1111 = 1:16 Postscale

bit 2 **TMR2ON:** Timer2 On bit
1 = Timer2 is on
0 = Timer2 is off

bit 1-0 **T2CKPS<1:0>:** Timer2 Clock Prescale Select bits
00 = Prescaler is 1
01 = Prescaler is 4
1x = Prescaler is 16

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

TABLE 8-1: ECCP MODE - TIMER RESOURCE

ECCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

8.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

An event is selected by control bits CCP1M<3:0> (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

8.1.1 CCP1 PIN CONFIGURATION

In Capture mode, the CCP1 pin should be configured as an input by setting the TRISB<3> bit.

Note:	If the RB3/CCP1/P1A pin is configured as an output, a write to the port can cause a capture condition.

8.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode. In Asynchronous Counter mode, the capture operation may not work.

8.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF following any such change in Operating mode.

8.1.4 ECCP PRESCALER

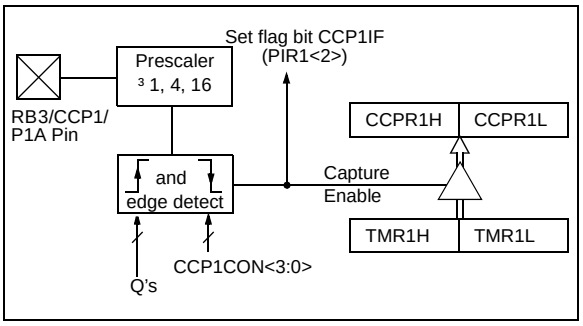
There are three prescaler settings, specified by bits CCP1M<3:0>. Whenever the ECCP module is turned off or the ECCP module is not in Capture mode, the prescaler counter is cleared. This means that any RESET will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 8-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 8-1: Changing Between Capture Prescalers

```
CLRF    CCP1CON     ; Turn ECCP module off
MOVLW   NEW_CAPT_PS ; Load WREG with the
                    ; new prescaler mode
                    ; value and ECCP ON
MOVWF   CCP1CON     ; Load CCP1CON with
                    ; this value
```

FIGURE 8-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



8.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the CCP1 pin is:

- driven High
- driven Low
- toggle output (High to Low or Low to High)
- remains Unchanged

The action on the pin is based on the value of control bits CCP1M<3:0>. At the same time, interrupt flag bit CCP1IF is set.

Changing the ECCP mode select bits to the clear output on Match mode (CCP1M<3.0> = “1000”) presets the CCP1 output latch to the logic 1 level. Changing the ECCP mode select bits to the clear output on Match mode (CCP1M<3:0> = “1001”) presets the CCP1 output latch to the logic 0 level.

8.2.1 CCP1 PIN CONFIGURATION

The user must configure the CCP1 pin as an output by clearing the appropriate TRISB bit.

Note:	Clearing the CCP1CON register will force the CCP1 compare output latch to the default low level. This is not the port data latch.

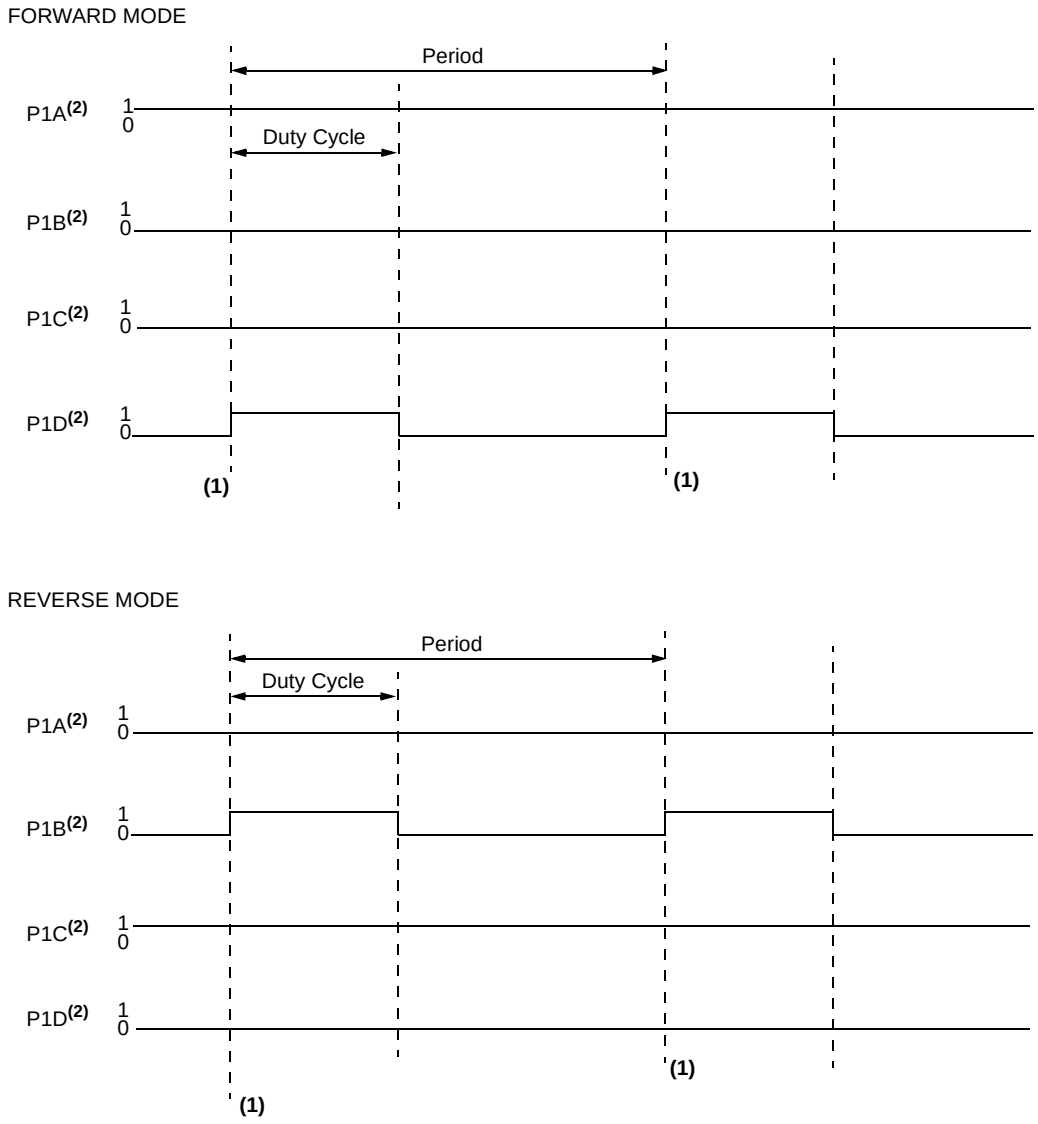
8.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the ECCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

In Full-Bridge Output mode, four pins are used as outputs; however, only two outputs are active at a time. In the Forward mode, RB3/CCP1/P1A pin is continuously active, and RB7/T1OSI/P1D pin is modulated. In the Reverse mode, RB6/T1OSO/T1CKI/P1C pin is continuously active, and RB5/SDO/P1B pin is modulated.

P1A, P1B, P1C and P1D outputs are multiplexed with PORTB<3> and PORTB<5:7> data latches. TRISB<3> and TRISB<5:7> bits must be cleared to make the P1A, P1B, P1C, and P1D pins output.

FIGURE 8-8: FULL-BRIDGE PWM OUTPUT



Note 1: At this time, the TMR2 register is equal to the PR2 register.
2: Output signal is shown as asserted high.

8.3.5 PROGRAMMABLE DEADBAND DELAY

In half-bridge or full-bridge applications, driven by half-bridge outputs (see Figure 8-7), the power switches normally require longer time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches will be on for a short period of time, until one switch completely turns off. During this time, a very high current, called shoot-through current, will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on the power switch is normally delayed to allow the other switch to completely turn off.

In the Half-Bridge Output mode, a digitally programmable deadband delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 8-6 for illustration. The P1DEL register sets the amount of delay.

REGISTER 8-2: PWM DELAY REGISTER (P1DEL: 97H)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
P1DEL7	P1DEL6	P1DEL5	P1DEL4	P1DEL3	P1DEL2	P1DEL1	P1DEL0
bit 7							bit 0

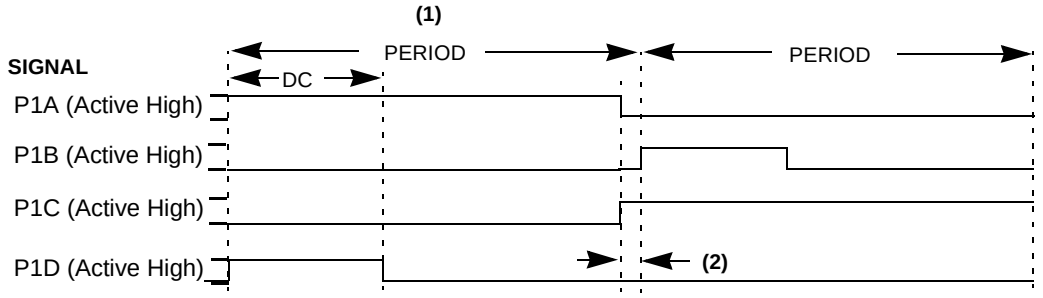
bit 7-0 **P1DEL<7:0>: PWM Delay Count for Half-Bridge Output Mode:** Number of FOSC/4 (Tosc•4) cycles between the P1A transition and the P1B transition.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

8.3.6 DIRECTION CHANGE IN FULL-BRIDGE OUTPUT MODE

In the Full-Bridge Output mode, the PWM1M1 bit in the CCP1CON register allows user to control the Forward/ Reverse direction. When the application firmware changes this direction control bit, the ECCP module will assume the new direction on the next PWM cycle. The current PWM cycle still continues, however, the non-modulated outputs, P1A and P1C signals, will transition to the new direction TOSC, 4•TOSC or 16•TOSC (for Timer2 prescale T2CKRS<1:0> = 00, 01 and 1x respectively) earlier, before the end of the period. During this transition cycle, the modulated outputs, P1B and P1D, will go to the inactive state. See Figure 8-10 for illustration.

FIGURE 8-10: PWM DIRECTION CHANGE



Note 1: The Direction bit in the ECCP Control Register (CCP1CON<PWM1M1>) is written anytime during the PWM cycle.
2: The P1A and P1C signals switch TOSC, 4*Tosc or 16*TOSC, depending on the Timer2 prescaler value, earlier when changing direction. The modulated P1B and P1D signals are inactive at this time.

When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. Buffer full bit, BF (SSPSTAT<0>), indicates when the SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the MSSP Interrupt is used to determine when the transmission/reception has completed. The SSPBUF must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 9-1 shows the loading of the SSPBUF (SSPSR) for data transmission.

EXAMPLE 9-1: Loading the SSPBUF (SSPSR) Register

```
      BSF   STATUS, RP0    ;Specify Bank 1
LOOP  BTFSS SSPSTAT, BF    ;Has data been
                           ;received
                           ;(xmit complete)?
      GOTO  LOOP           ;No
      BCF   STATUS, RP0    ;Specify Bank 0
      MOVF  SSPBUF, W      ;Save SSPBUF...
      MOVWF RXDATA         ;...in user RAM
      MOVF  TXDATA, W      ;Get next TXDATA
      MOVWF SSPBUF         ;New data to xmit
```

The SSPSR is not directly readable or writable, and can only be accessed by addressing the SSPBUF register. Additionally, the MSSP STATUS register (SSPSTAT) indicates the various status conditions.

9.1.2 ENABLING SPI I/O

To enable the serial port, MSSP Enable bit, SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear bit SSPEN, re-initialize the SSPCON registers, and then set bit SSPEN. This configures the SDI, SDO, SCK and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed. That is:

- SDI is automatically controlled by the SPI module
- SDO must have TRISB<5> cleared
- SCK (Master mode) must have TRISB<2> cleared
- SCK (Slave mode) must have TRISB<2> set
- $\overline{SS}$ must have TRISB<1> set, and ANSEL<5> cleared

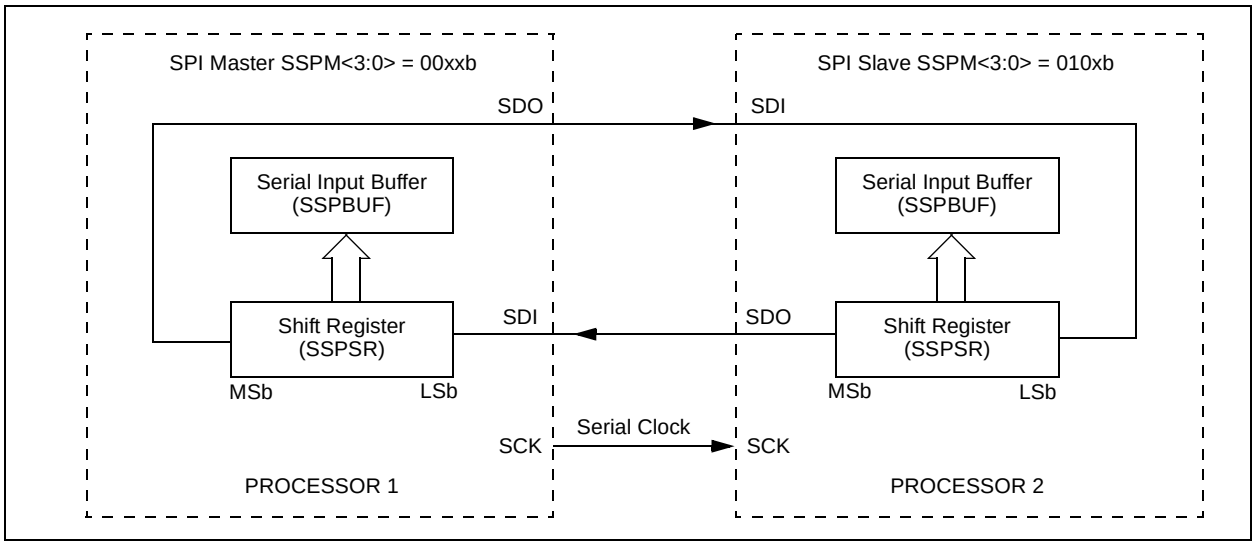
Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value.

9.1.3 TYPICAL CONNECTION

Figure 9-2 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge, and latched on the opposite edge of the clock. Both processors should be programmed to same Clock Polarity (SSPCON<4>), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- Master sends data — Slave sends dummy data
- Master sends data — Slave sends data
- Master sends dummy data — Slave sends data

FIGURE 9-2: SPI MASTER/SLAVE CONNECTION



9.2.3 GENERAL CALL ADDRESS SUPPORT

The addressing procedure for the I^2C bus is such that the first byte after the START condition usually determines which device will be the slave addressed by the master. The exception is the general call address, which can address all devices. When this address is used, all devices should, in theory, respond with an Acknowledge.

The general call address is one of eight addresses reserved for specific purposes by the I^2C protocol. It consists of all 0's with R/$\overline{W}$ = 0

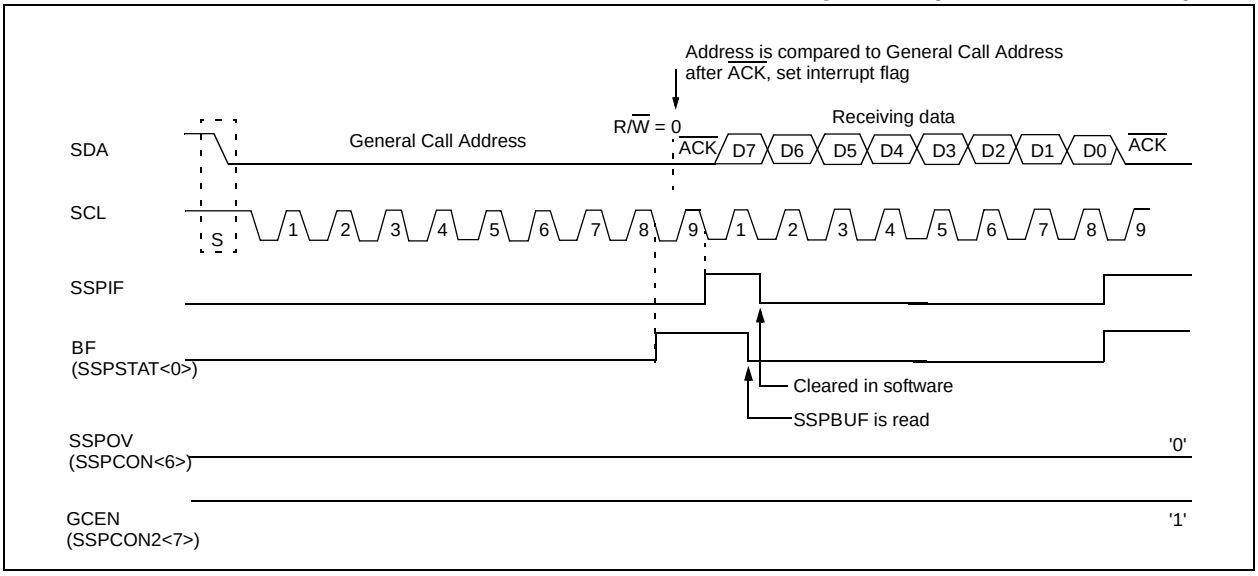
The general call address is recognized when the General Call Enable bit (GCEN) is set (SSPCON2<7> is set). Following a START bit detect, eight bits are shifted into the SSPSR, and the address is compared against SSPADD. It is also compared to the general call address, fixed in hardware.

If the general call address matches, the SSPSR is transferred to the SSPBUF, the BF flag is set (eighth bit), and on the falling edge of the ninth bit ($\overline{ACK}$ bit), the SSPIF flag is set.

When the interrupt is serviced, the source for the interrupt can be checked by reading the contents of the SSPBUF to determine if the address was device specific or a general call address.

If the general call address is sampled with GCEN set and the slave configured in 10-bit Address mode, the second half of the address is not necessary. The UA bit will not be set and the slave will begin receiving data after the Acknowledge (Figure 9-12).

FIGURE 9-12: SLAVE MODE GENERAL CALL ADDRESS SEQUENCE (7- OR 10-BIT MODE)



11.10 A/D Operation During SLEEP

The A/D module can operate during SLEEP mode. This requires that the A/D clock source be configured for RC (ADCS<1:0> = 11b). With the RC clock source selected, when the GO/DONE bit is set the A/D module waits one instruction cycle before starting the conversion cycle. This allows the SLEEP instruction to be executed, which eliminates all digital switching noise during the sample and conversion. When the conversion cycle is completed the GO/DONE bit is cleared, and the result loaded into the ADRESH and ADRESL registers. If the A/D interrupt is enabled, the device will wake-up from SLEEP. If the A/D interrupt is not enabled, the A/D module will then be turned off, although the ADON bit will remain set.

When the A/D clock source is another clock option (not RC), a SLEEP instruction causes the present conversion to be aborted and the A/D module is turned off, though the ADON bit will remain set.

Turning off the A/D places the A/D module in its lowest current consumption state.

Note:	For the A/D module to operate in SLEEP, the A/D clock source must be configured to RC (ADCS<1:0> = 11).

11.11 Connection Considerations

Since the analog inputs employ ESD protection, they have diodes to VDD and VSS. This requires that the analog input must be between VDD and VSS. If the input voltage exceeds this range by greater than 0.3V (either direction), one of the diodes becomes forward biased and it may damage the device if the input current specification is exceeded.

An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 2.5 kΩ recommended specification. It is recommended that any external components connected to an analog input pin (capacitor, zener diode, etc.) have very little leakage current.

TABLE 11-2: SUMMARY OF A/D REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	-0-- 0000	-0-- 0000
8Ch	PIE1	—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	-0-- 0000	-0-- 0000
1Eh	ADRESH	A/D High Byte Result Register								xxxx xxxx	uuuu uuuu
9Eh	ADRESL	A/D Low Byte Result Register								xxxx xxxx	uuuu uuuu
9Bh	REFCON	VRHEN	VRLEN	VRHOEN	VRLOEN	—	—	—	—	0000 ----	0000 ----
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	CHS3	ADON	0000 0000	0000 0000
9Fh	ADCON1	ADFM	VCFG2	VCFG1	VCFG0	—	—	—	—	0000 ----	0000 ----
05h	PORTA	PORTA Data Latch when written: PORTA pins when read								000x 0000	000u 0000
06h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xx11	uuuu uu11
85h	TRISA	PORTA Data Direction Register								1111 1111	1111 1111
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
9Dh	ANSEL	—	—	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
17h	CCP1CON	—	—	—	—					0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D conversion.

12.8 Time-out Sequence

On power-up, the time-out sequence is as follows: First PWRT time-out is invoked by the POR pulse. When the PWRT delay expires, the Oscillator Start-up Timer is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 12-6, Figure 12-7, Figure 12-8 and Figure 12-9 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{MCLR}$ high will begin execution immediately (Figure 12-8). This is useful for testing purposes or to synchronize more than one PIC® microcontroller operating in parallel.

Table 12-5 shows the RESET conditions for some special function registers, while Table 12-6 shows the RESET conditions for all the registers.

12.9 Power Control/STATUS Register (PCON)

The Power Control/STATUS Register, PCON, has two status bits that provide indication of which power-up type RESET occurred.

Bit0 is Brown-out Reset Status bit, $\overline{BOR}$. The $\overline{BOR}$ bit is unknown upon a POR. $\overline{BOR}$ must be set by the user and checked on subsequent RESETS to see if bit $\overline{BOR}$ cleared, indicating a BOR occurred.

Bit1 is $\overline{POR}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 12-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out	Wake-up from SLEEP
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1		
XT, HS, LP	TPWRT + 1024TOSC	1024TOSC	TPWRT + 1024TOSC	1024TOSC
EC, ER, INTRC	TPWRT	—	TPWRT	—

TABLE 12-4: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{POR}$	$\overline{BOR}$	$\overline{TO}$	$\overline{PD}$	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
0	x	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{MCLR}$ Reset during normal operation
1	1	1	0	$\overline{MCLR}$ Reset during SLEEP or interrupt wake-up from SLEEP

TABLE 12-5: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	---- 1-0x
$\overline{MCLR}$ Reset during normal operation	000h	000u uuuu	---- 1-uu
$\overline{MCLR}$ Reset during SLEEP	000h	0001 0uuu	---- 1-uu
WDT Reset	000h	0000 1uuu	---- 1-uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- u-uu
Brown-out Reset	000h	0001 1uuu	---- 1-u0
Interrupt wake-up from SLEEP, GIE = 0	PC + 1	uuu1 0uuu	---- u-uu
Interrupt wake-up from SLEEP, GIE = 1	0004h	uuu1 0uuu	---- u-uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

SUBLW	Subtract W from Literal
Syntax:	[*label*] SUBLW k
Operands:	$0 \le k \le 255$
Operation:	k - (W) → (W)
Status Affected:	C, DC, Z
Description:	The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

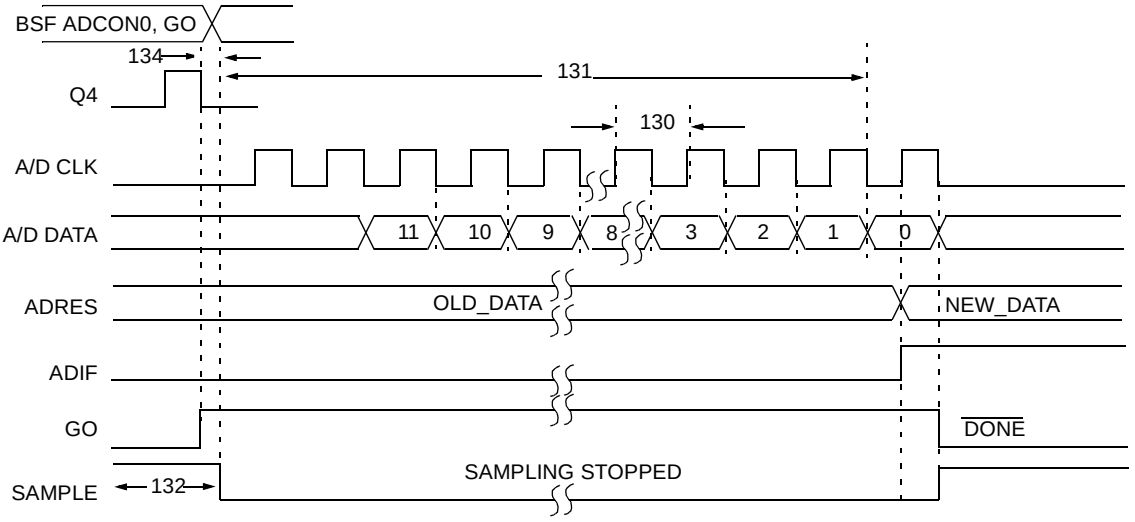
SUBWF	Subtract W from f
Syntax:	[*label*] SUBWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - (W) → (destination)
Status Affected:	C, DC, Z
Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

SWAPF	Swap Nybbles in f
Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (destination<7:4>), (f<7:4>) → (destination<3:0>)
Status Affected:	None
Description:	The upper and lower nybbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.

XORLW	Exclusive OR Literal with W
Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

FIGURE 15-15: PIC16C770/771 AND PIC16LC770/771 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D RC clock source is selected, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 15-13: PIC16C770/771 AND PIC16LC770/771 A/D CONVERSION REQUIREMENT (SLEEP MODE)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130*(3)	TAD	A/D Internal RC oscillator period	3.0	6.0	9.0	µs	ADCS<1:0> = 11 (RC mode) At VDD= 3.0V
			2.0	4.0	6.0	µs	At VDD = 5.0V
131*	TCNV	Conversion time (not including acquisition time) **(Note 1)**	—	13TAD	—	—	
132*	TACQ	Acquisition Time	**(Note 2)**	11.5	—	µs	
			5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1LSb (i.e., 1mV @ 4.096V) from the last sampled voltage (as stated on CHOLD).
134*	TGO	Q4 to A/D clock start	—	TOSC/2 + TCY	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

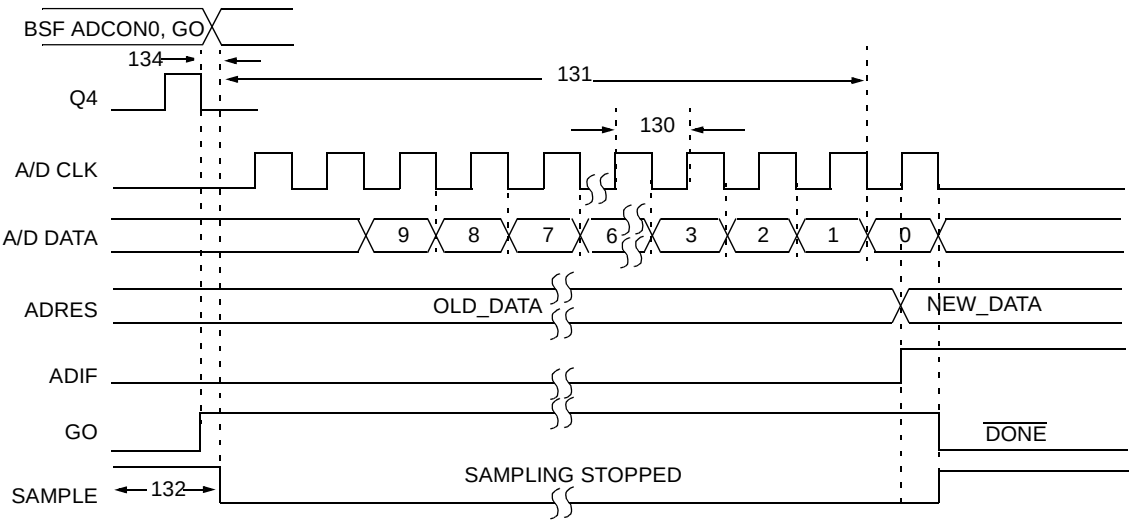
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 11.6 for minimum conditions.

3: These numbers multiplied by 8 if VRH or VRL is selected as A/D reference.

FIGURE 15-17: PIC16C717 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D RC clock source is selected, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 15-16: PIC16C717 AND PIC16LC717 A/D CONVERSION REQUIREMENT (SLEEP MODE)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130*(3)	TAD	A/D clock period	3.0	6.0	9.0	µs	ADCS<1:0> = 11 (A/D RC mode) At VDD = 3.0V
			2.0	4.0	6.0	µs	At VDD = 5.0V
131*	TCNV	Conversion time (not including acquisition time) **(Note 1)**	—	11TAD	—	—	
132*	TACQ	Acquisition Time	**(Note 2)**	11.5	—	µs	
			5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1LSb (i.e., 1mV @ 4.096V) from the last sampled voltage (as stated on CHOLD).
134*	TGO	Q4 to A/D clock start	—	TOSC/2 + TCY	—	—	If the A/D RC clock source is selected, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 11.6 for minimum conditions.

3: These numbers multiplied by 8 if VRH or VRL is selected as A/D reference.

FIGURE 16-30: VOH VS. IOH (-40°C TO +125°C, VDD = 5.0V)

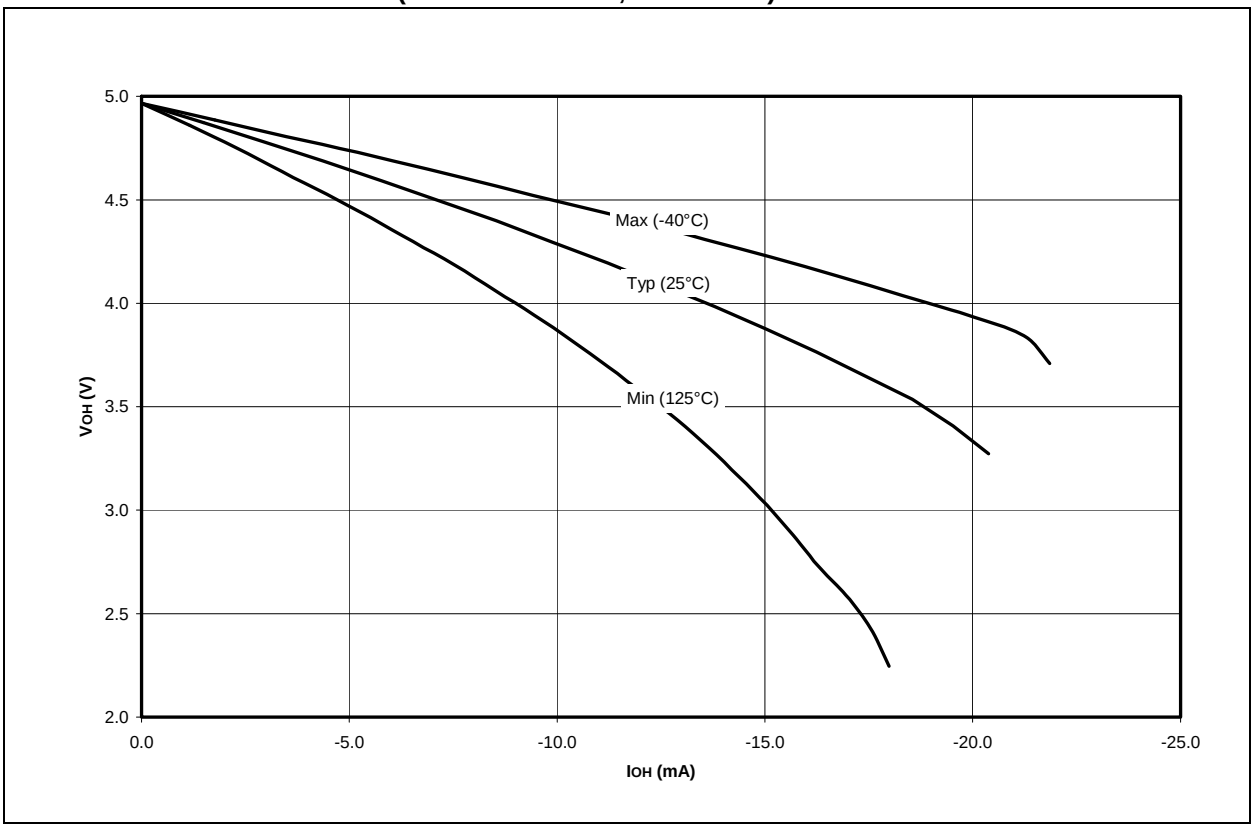
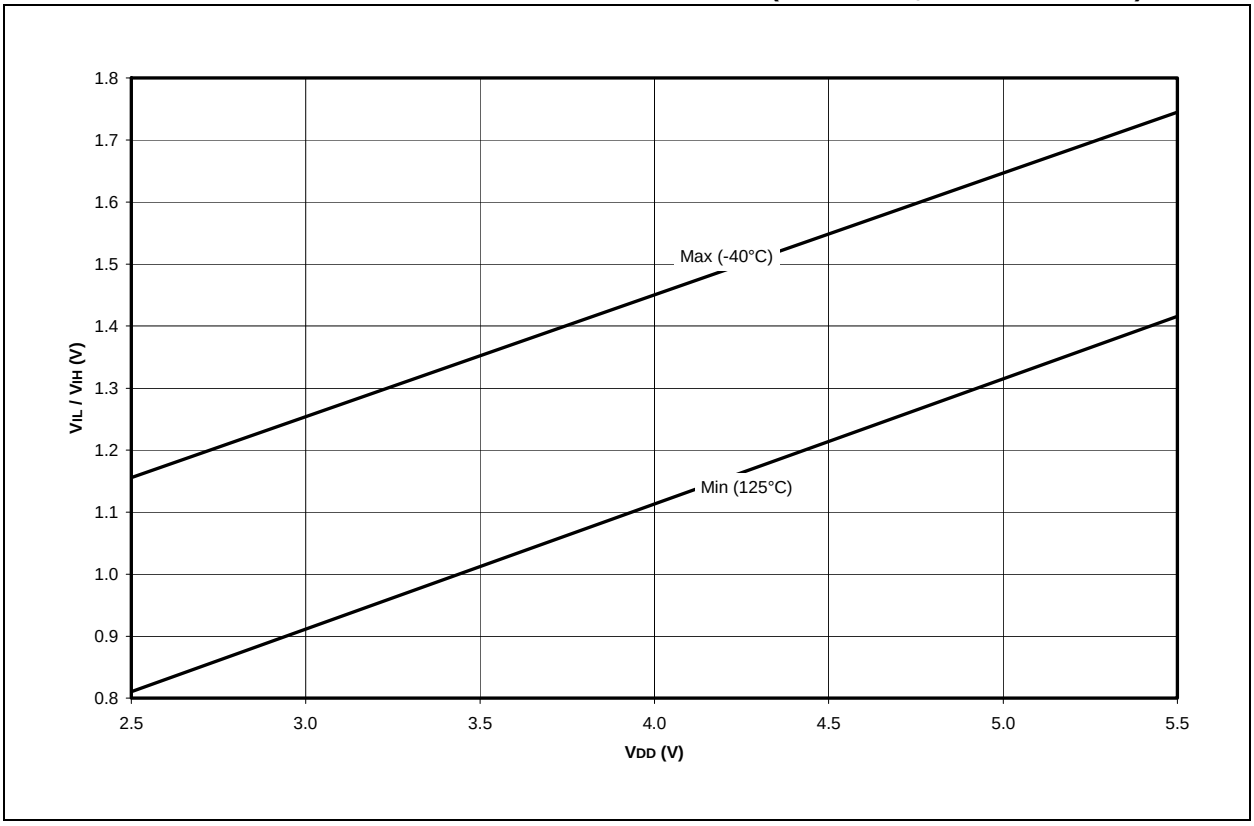
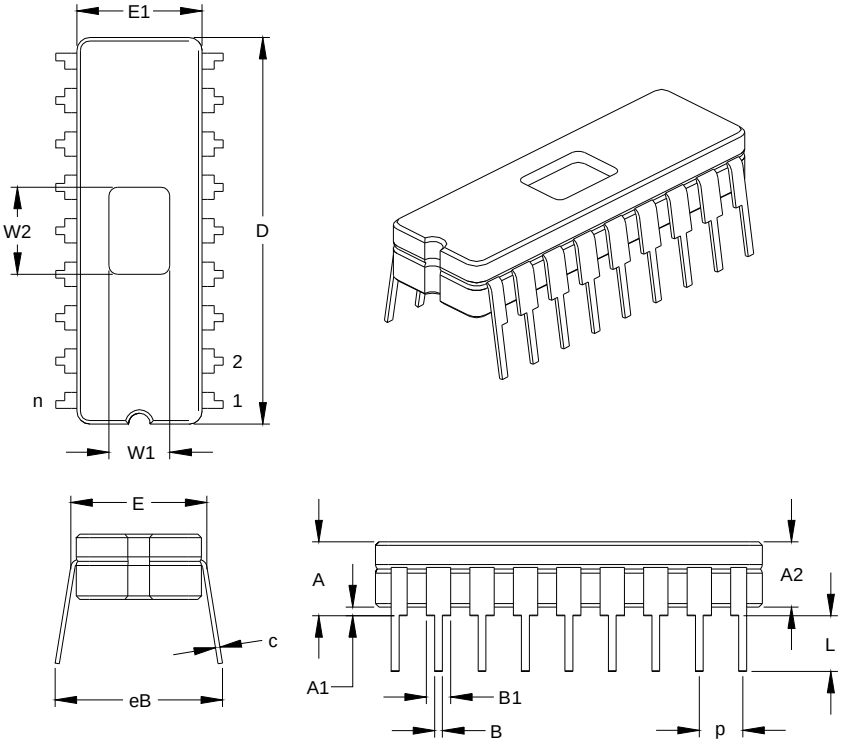


FIGURE 16-31: MINIMUM AND MAXIMUM VIH/VIL VS. VDD (TTL INPUT,-40°C TO +125°C)



17.3 18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

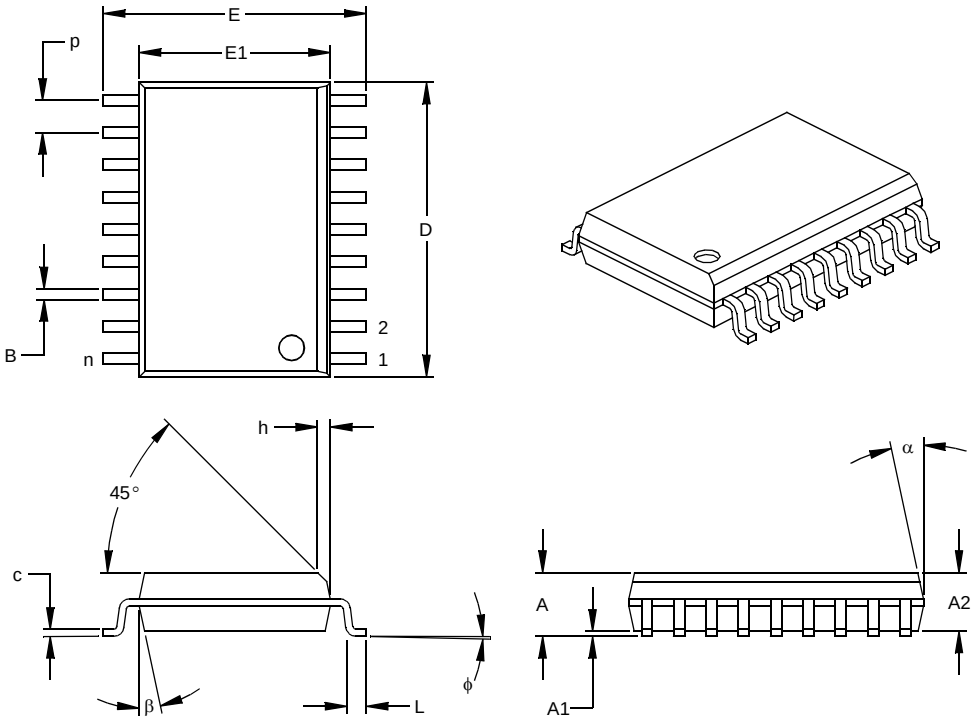


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

*Controlling Parameter
JEDEC Equivalent: MO-036
Drawing No. C04-010

17.4 18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

NOTES:

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